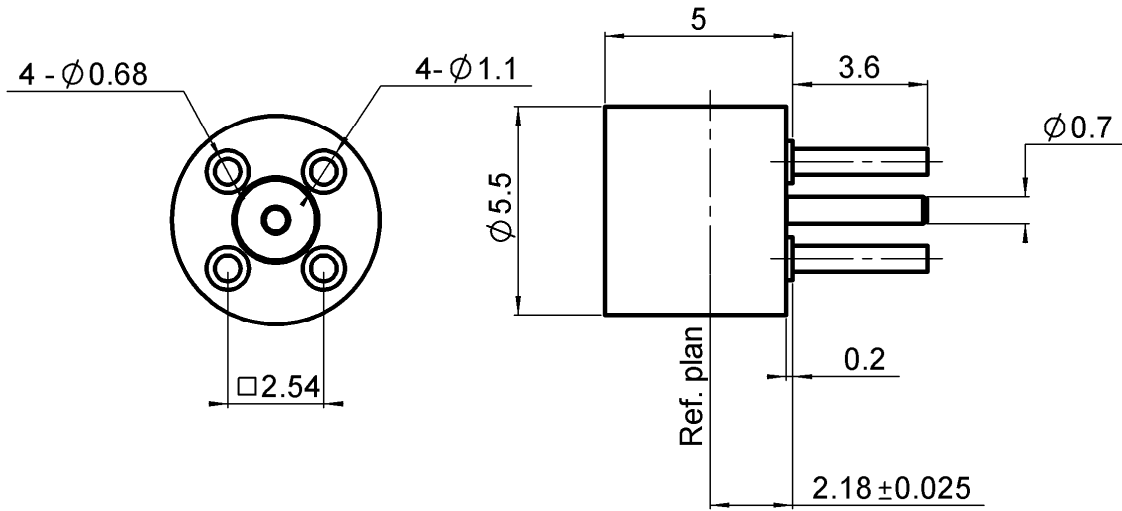


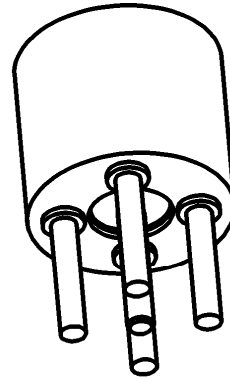
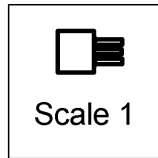
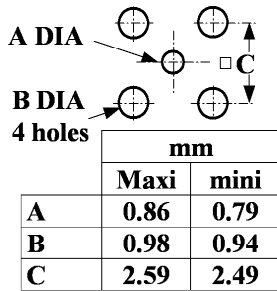
MALE STRAIGHT RECEPTACLE FOR PCB
SOLDER LEGS - FULL DETENT

R222.426.020

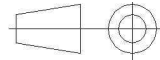
Series : SMP



PANEL CUT OUT



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	STAINLESS STEEL	GOLD 0.5 OVER NICKEL 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 1.27 OVER NICKEL 1.27
OUTER CONTACT	-	-
INSULATOR	PTFE	-
GASKET	-	-
OTHERS PARTS	-	-
-	-	-
-	-	-

Issue : 0949 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



MALE STRAIGHT RECEPTACLE FOR PCB

R222.426.020

SOLDER LEGS - FULL DETENT

Series : SMP

PACKAGING

SPECIFICATION

Standard	Unit	Other
100	'W' option	Contact us

ELECTRICAL CHARACTERISTICS

ENVIRONMENTAL

Impedance	50	Ω
Frequency	0-12	GHz
VSWR	1.15* + 0,0000	x F(GHz) Maxi
Insertion loss	0.12*	\sqrt{F} (GHz) dB Maxi
RF leakage	- (- F(GHz)) dB Maxi
Voltage rating	335	Veff Maxi
Dielectric withstanding voltage	500	Veff mini
Insulation resistance	5000	M Ω mini

Operating temperature	-65/+165	$^{\circ}$ C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

OTHERS CHARACTERISTICS

Assembly instruction

Others :

*Coaxial Transmission Line Only

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating end	6.8	N mini
Axial force – Opposite end	NA	N mini
Torque	NA	N.cm mini
Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm
Mating life	100	Cycles mini
Weight	0,7200	g

Issue : 0949 B

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MALE STRAIGHT RECEPTACLE FOR PCB

R222.426.020

SOLDER LEGS - FULL DETENT

Series : SMP

SOLDER PROCEDURE IN INDUSTRIAL ENVIRONMENT

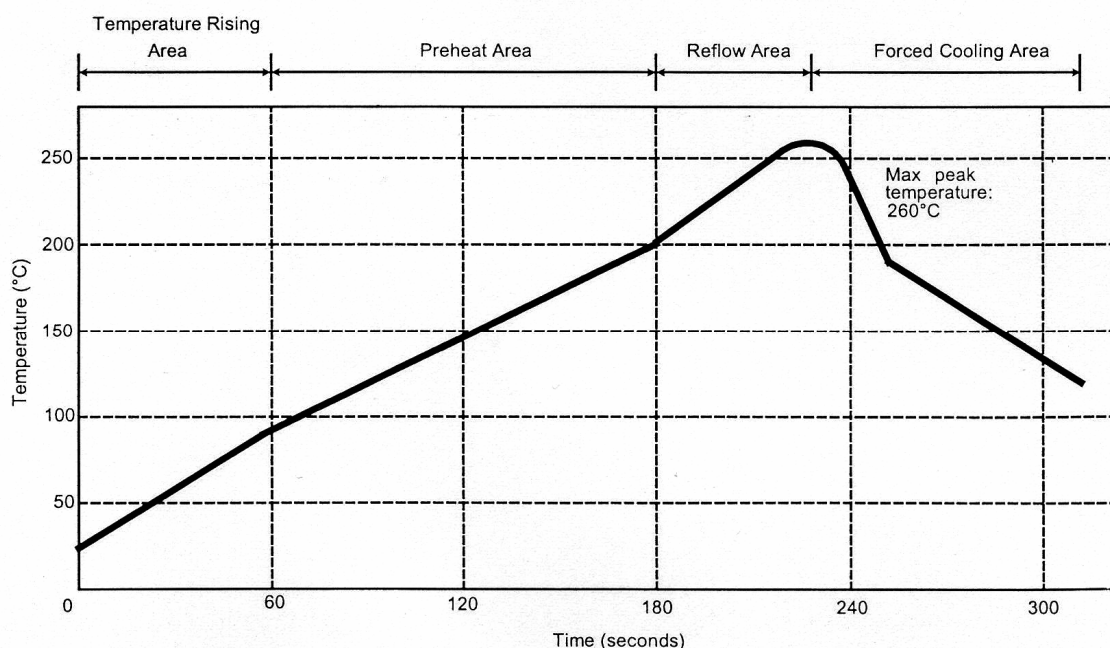
Suite au nouvelles directives européennes RoHS, le plomb ne doit plus être utilisé, entre autre, dans les procédés de brasage

Following the new European directives RoHS, lead should not be used any more, in the solder process.

Voici donc la nouvelle pâte à braser et le nouveau profil de température à utiliser :

Here follow the new solder paste and a new temperature profile to be used:

Sn AG4 Cu0.5



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

Issue : 0949 B

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